

03-11-2002



102008558

To the Honorable Commissioner of Patents a
copy thereof.

attached original documents or

1. Name of Conveying party(ies): **Lisa A. Fanti, Randolph F. Knarr, Erik J. Roggeman,
Kamalesh K. Srivastava****NRD 2-19-02**3. Nature of Conveyance: **Assignment**Execution Date: **02/13/02, 02/12/02,
02/12/02, 02/12/02**

2. Name & address of receiving party(ies)

Name:

**International Business
Machines Corporation**

Street

Address: **New Orchard Road**City: **Armonk** State: **New York** ZIP: **10504****JCT14 U.S. PTO
10/078948
02/19/02**

4. Application number(s) or patent number(s):

10078948Title of Application: **SACRIFICIAL SEED LAYER PROCESS FOR FORMING C4 SOLDER BUMPS**If this document is being filed together with a new application, the execution date of the
application is: **02/13/02, 02/12/02, 02/12/02, 02/12/02**A. Patent Application No(s).
Docket No. **fis920010149US1**
Serial No.

B. Patent No(s)

Additional numbers attached? Yes X No5. Name and address of party to whom
correspondence concerning document
should be mailed:Name: **Graham S. Jones, II**

Street Address:

**42 Barnard Avenue
Poughkeepsie, NY 12601-5023**6. Total number of applications and
patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

EnclosedX Authorized to be charged to
deposit account8. Deposit A/C no.: **09-0458 (FI-059)**
(Attach duplicate copy of this page
if paying by deposit account)**03/08/2002 DBYRNE 00000241 090458 10078948****01 FC:581 40.00 CH**

DO NOT USE THIS SPACE

9. Statement of signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any
attached copy is a true copy of the original document.**Ira D. Blecker, Reg.# 29,894**

Name of Person Signing

Telephone No. (845) 894-2580

Signature

Date

Total number of pages, including cover sheet, attachments, and document 3**Express Mail No. ET926726347US**I hereby certify that this correspondence is being deposited with the United States Postal Service as
Express Mail in an envelope addressed to: UNITED STATES PATENT AND TRADEMARK OFFICE, PO BOX 2327,
ARLINGTON, VA 22202. Applicant and/or Attorney requests the date of deposit
as the filing date. Date of Deposit: **February 19, 2002** Depositor: **Karen Cing-Mars****Karen Cing-Mars 2/19/02****PATENT
REEL: 012645 FRAME: 0035**

ASSIGNMENT

WHEREAS, WE

- | | |
|----------------------------------------------------------------|----------------------------------------------------------------|
| (1) Lisa A. Fanti
County of Dutchess | of Hopewell Junction,
State of New York 12533 |
| (2) Randolph F. Knarr
County of Westchester | of Goldens Bridge,
State of New York 10526 |
| (3) Erik J. Roggeman
County of Dutchess | of Fishkill,
State of New York 12524 |
| (4) Kamalesh K. Srivastava
County of Dutchess | of Wappingers Falls,
State of New York 12590 |

have invented certain improvements in

Sacrificial Seed Layer Process for Forming C4 Solder Bumps

and executed a United States patent application therefor on:

(dates that Inventors signed the declaration)

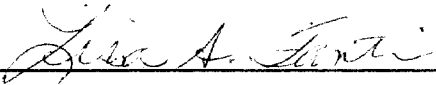
- 1) 2/13, 2002,
- 2) 2/12, 2002,
- 3) 2/12/, 2002,
- 4) 02/12/, 2002,

Whereas, **INTERNATIONAL BUSINESS MACHINES CORPORATION**, a corporation of **New York**, having a place of business at **Armonk, New York 10504**, (hereinafter called **IBM**), desires to acquire the entire, right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed

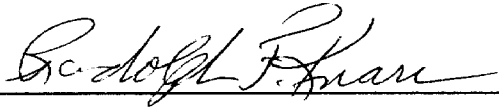
1) at East Fishkill
city


Signature of inventor

on 2/13, 2002
date

Lisa A. Fanti
Typed Name of inventor

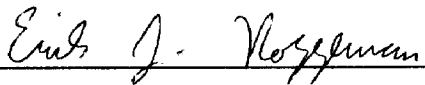
2) at East Fishkill, NY
city


Signature of inventor

on 2/12, 2002
date

Randolph F. Knarr
Typed Name of inventor

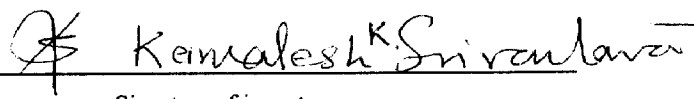
3) at East Fishkill, NY
city


Signature of inventor

on 2/12, 2002
date

Erik J. Roggeman
Typed Name of inventor

4) at East Fishkill, NY
city


Signature of inventor

on 02/12/02, 2002
date

Kamallesh K. Srivastava
Typed Name of inventor